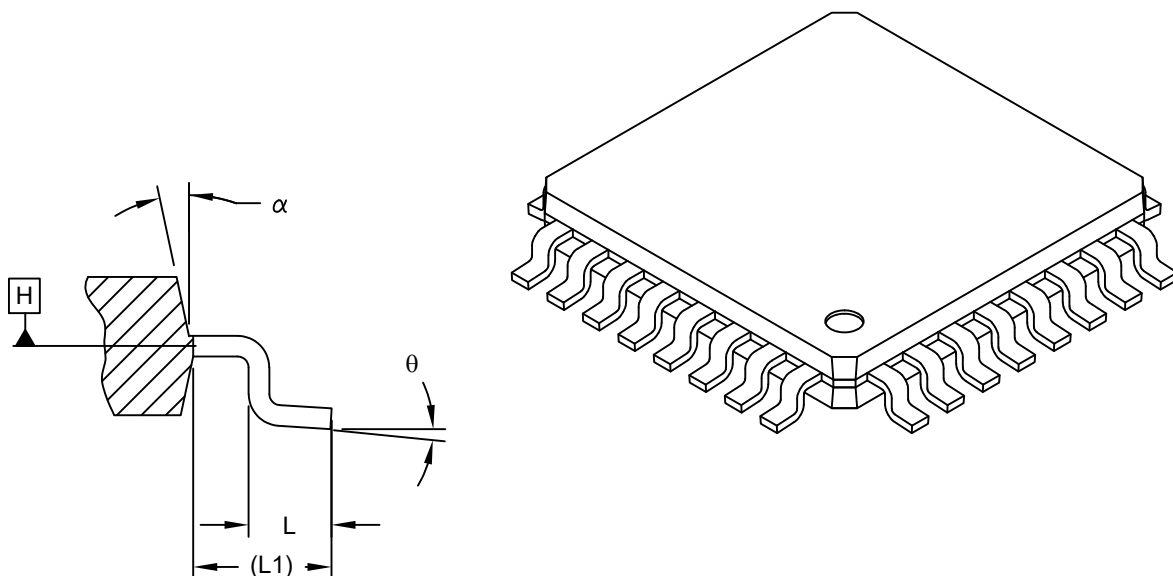


32-Lead Plastic Thin Quad Flatpack (T5X) - 7x7x1.0 mm Body [TQFP] 2.00 mm Footprint; Also Atmel Legacy Global Package Code AUT

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



SECTION A-A

Dimension	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Leads	N	32		
Lead Pitch	e	0.80 BSC		
Overall Height	A	-	-	1.20
Standoff	A1	0.05	-	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	θ	0°	-	7°
Overall Width	E	9.00 BSC		
Overall Length	D	9.00 BSC		
Molded Package Width	E1	7.00 BSC		
Molded Package Length	D1	7.00 BSC		
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	-	13°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.